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(12) United States Design Patent

Lee et al.

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(54) **SEMICONDUCTOR DEVICE**

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(**) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/101, 110, 112, 118, 120, 123, 133, D13/146, 147, 159, 154, 156, 174, 182, D13/184, 199; D14/356, 433, 435, 438
CPC H01R 24/00; H01R 12/00; H01R 12/70; H01R 13/62
See application file for complete search history.

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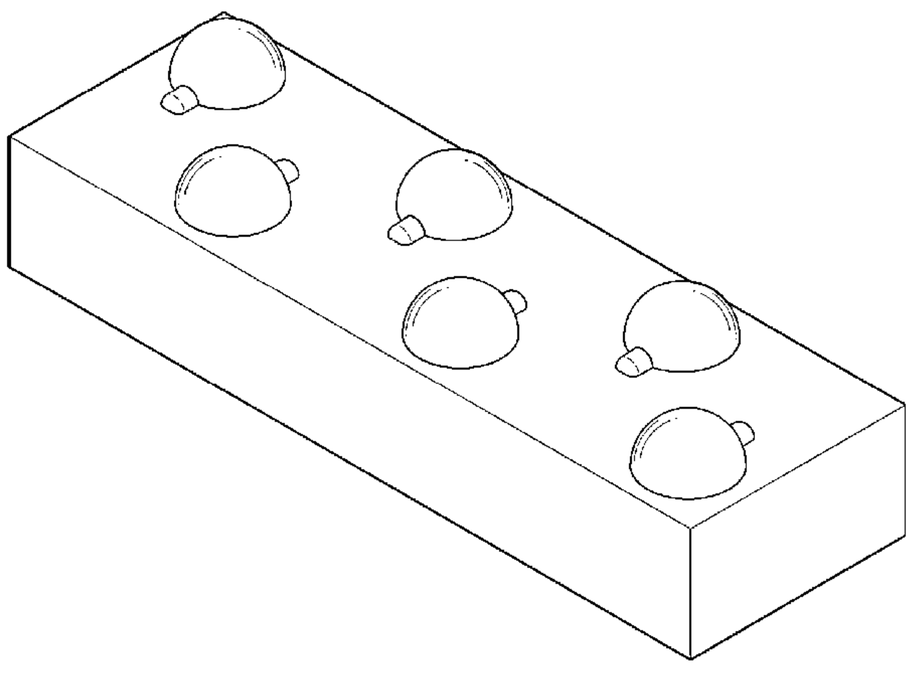
(57) **CLAIM**

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. **1** is a front, top, and right-side perspective view of a semiconductor device showing our new design;
FIG. **2** is a front view thereof;
FIG. **3** is a back view thereof;
FIG. **4** is a left-side view thereof;
FIG. **5** is a right-side view thereof;
FIG. **6** is a top view thereof; and,
FIG. **7** is a bottom view thereof.

1 Claim, 2 Drawing Sheets



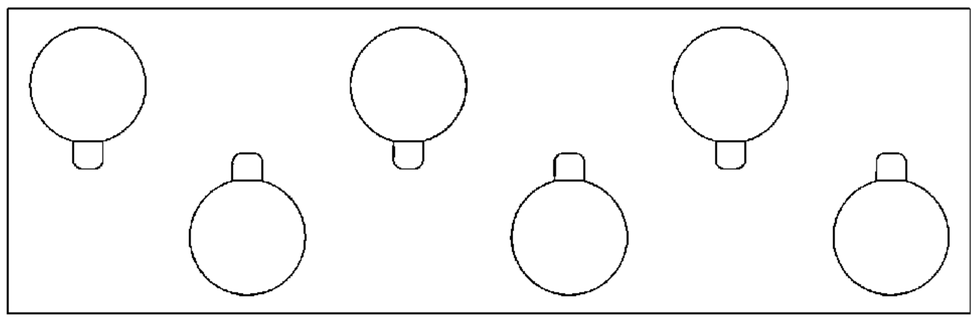


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FIG. 1

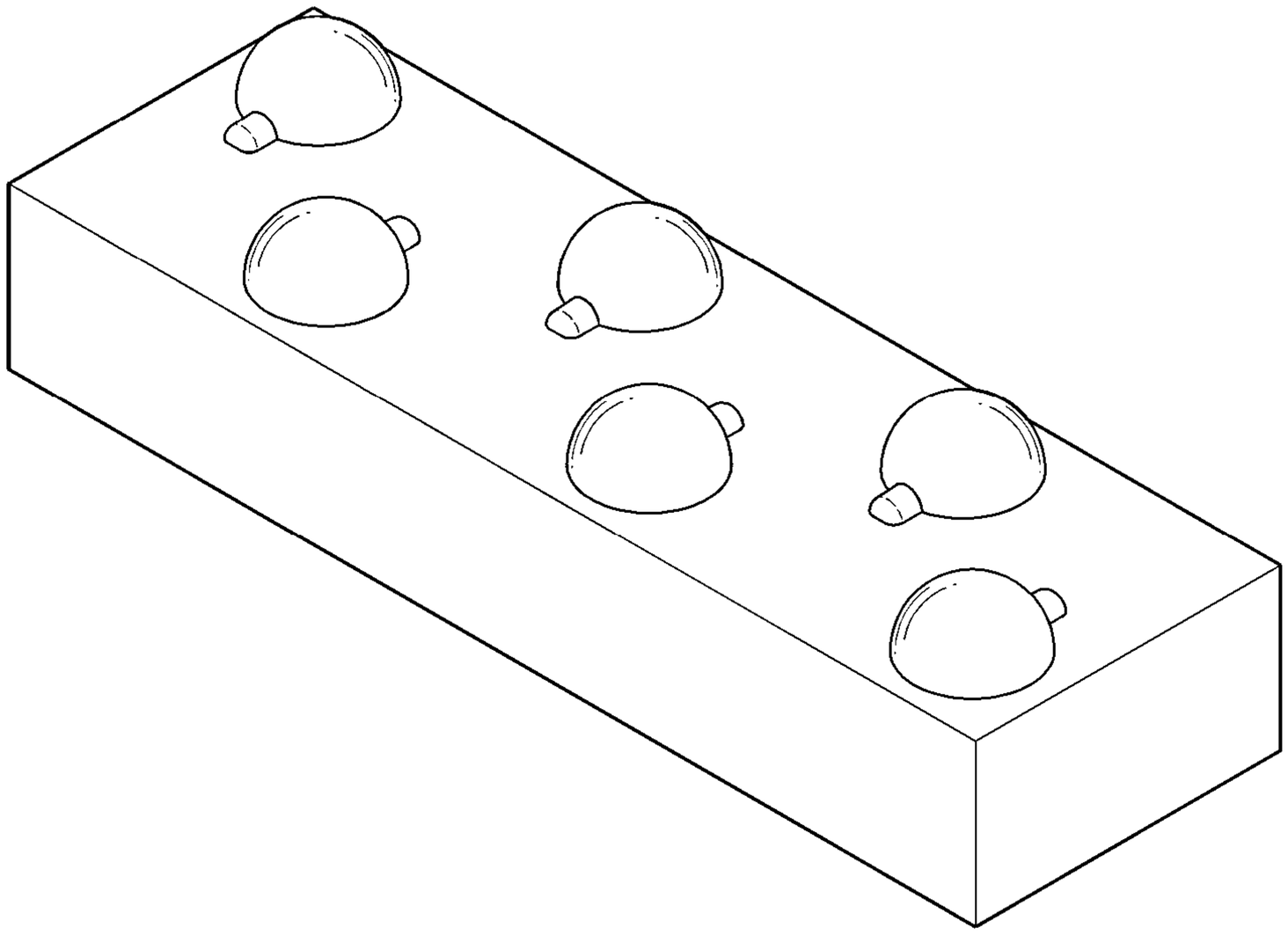

FIG. 2

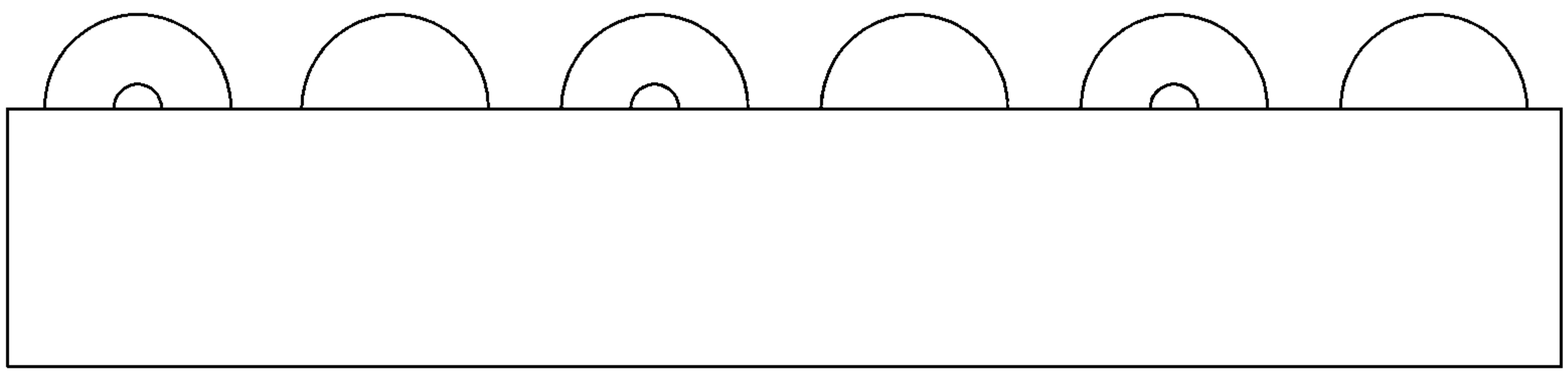

FIG. 3

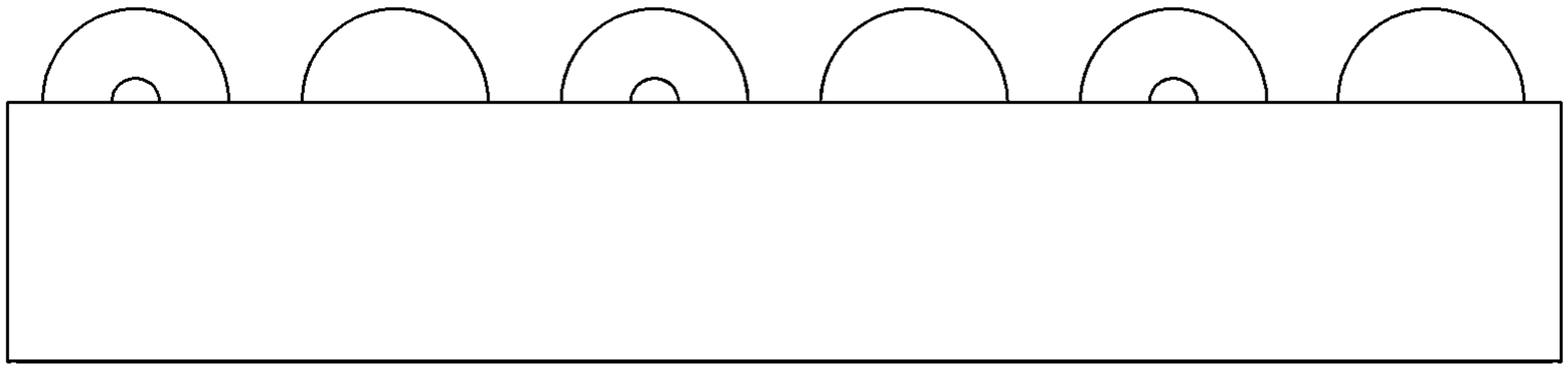

FIG. 4

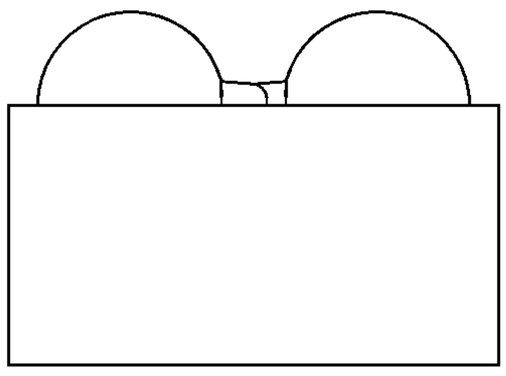

FIG. 5

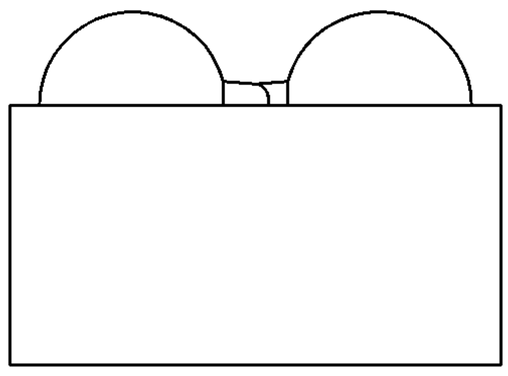

FIG. 6

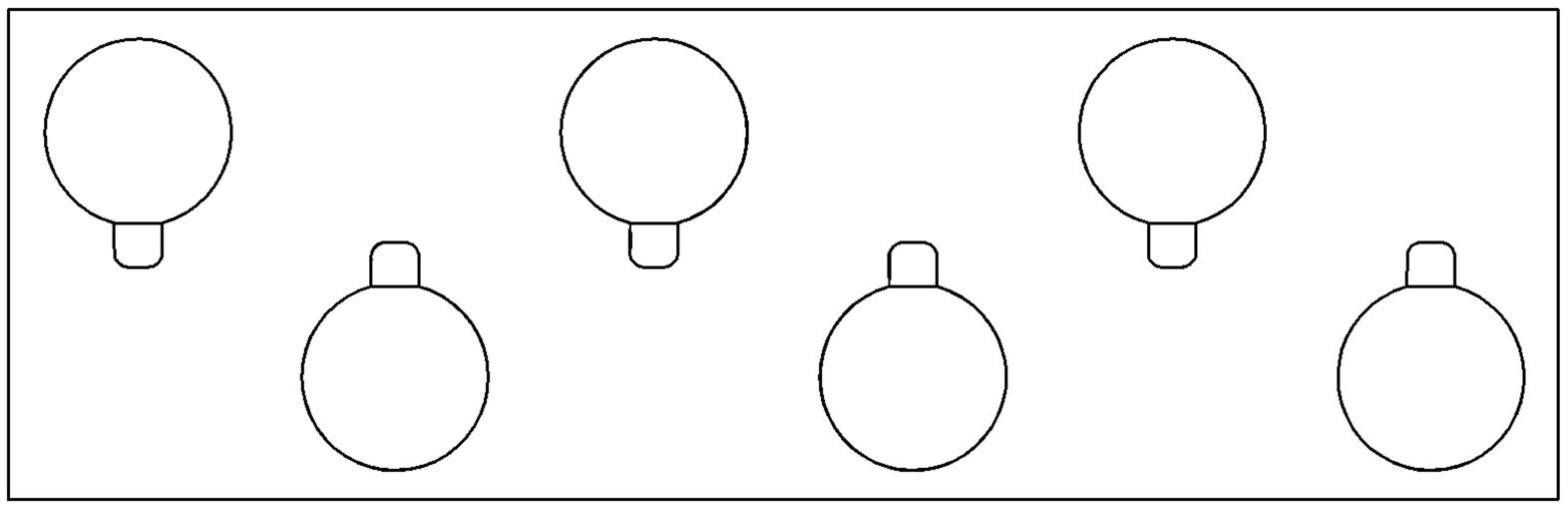

FIG. 7